

U.S. Patent Application Serial No. 10/776,714
Reply to Office Action dated April 12, 2006

Remarks

In the subject Action, the Examiner rejected claims 9-11 and 14. Applicant has amended claims 9. Applicant has also added new claims 20-22. Support of the amendments can at least be found in FIG. 6 of the specification. Claims 9-11, 14, and 20-22 remain pending in the present application. In light of the foregoing amendments and the following remarks, Applicant respectfully requests withdrawal of the pending rejections and advancement of this application to allowance.

Rejections Under 35 U.S.C. §102

In the Office Action, the Examiner rejected claims 9 and 14 as being anticipated by Liu et al. under §102(b). Applicant respectfully traverses the rejection in view of the amendments to claim 9 above and the arguments below.

Claim 9 recites that "*an exposed portion of the probe pad has a mark-shape contour* to indicate the relative location of the probe pad on the semiconductor circuit." (emphasis added) In contrast, Liu et al. fails to disclose or suggest that "*an exposed portion of the probe pad has a mark-shape contour* to indicate the relative location of the probe pad on the semiconductor circuit." Rather, Liu et al. discloses:

[a]fter electrical testing, a depressed print 38 is left in the testing area 34 on the surface of the bonding pad 32 as shown in FIG. 6. A passivation layer 40 is then formed on the surface of the semiconductor chip 30 as shown in FIG. 7. The passivation layer 40 comprises an inorganic passivation layer 42 formed of phosphosilicate glass (PSG) or silicon nitride positioned on the surface of the semiconductor chip 30 and an organic passivation layer 44 formed of polyimide positioned on the inorganic passivation layer 42. (emphasis added)

See, col. 3, ll. 17-26; Figs. 6-7. Liu et al. also discloses that "[e]tching is accomplished using plasma to form the passivation layer 40 with *an opening 46 for passivating the surface* of the semiconductor chip 30 as shown in FIG. 8." (emphasis added) See, col. 3, ll. 32-35; Fig. 8. In

U.S. Patent Application Serial No. 10/776,714
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other words, Liu et al. discloses that the depressed print 38 left in the testing area 34 is covered by a passivation layer 40, and the exposed portion 46 does not have a mark shape contour. Therefore, Liu et al. fails to suggest or disclose that "*an exposed portion of the probe pad has a mark-shape contour*" to indicate the relative location of the probe pad on the semiconductor circuit" as recited in claim 9 of the present application. It is thus submitted, for at least the reasons noted, that claim 9 is patentable.

Claim 14 is a dependent claim and is also allowable over the art of record. Applicant does not otherwise concede the correctness of the rejection and reserves the right to make additional arguments as may be necessary.

In view of the above, Applicant respectfully requests reconsideration and withdrawal of the pending rejections.

Rejections Under 35 U.S.C. §103

Next in the subject Action, the Examiner rejected claims 10-11 under §103(a) as being obvious over Liu et al. Applicant respectfully traverses this rejection.

As discussed above, independent claim 9 is patentable. Thus, dependent claims 10-11 are also allowable over the art of record. Applicant does not otherwise concede the correctness of the rejection and reserves the right to make additional arguments as may be necessary. Applicant respectfully requests reconsideration and withdrawal of the pending rejection.

New Claims

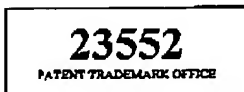
New claims 20-22 have been added.

U.S. Patent Application Serial No. 10/776,714
Reply to Office Action dated April 12, 2006

Conclusion

This response is believed to be responsive to all points raised in the Office Action. Accordingly, Applicant respectfully requests reconsideration and allowance of all of the currently pending claims. Should the Examiner have any remaining questions or concerns, the Examiner is urged to contact the undersigned attorney at 612.336.4611 to discuss the same.

Respectfully submitted,



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By

A handwritten signature in black ink, appearing to read "Tong Wu", written over a horizontal line.

Tong Wu
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TW:SZ